Automatic rotary head bonders
for thin aluminium wire from
25 to 50 μm. Suitable for hybrid,
COB and leadframe applications.
Series 6300 high speed, rotary head bonders for product development and efficient production

The series 6300 rotary head bonders are a family of fully automatic, high-speed, wedge-wedge bonders for 25 to 50 μm wire. They can be used for aluminium and gold wire applications.

**Optics/Pattern Recognition**

- Lighting: fibre optics with programmable direct and side lighting
- Focus: programmable per chip
- Camera: miniature CCD camera, 0.5 lux sensitivity, 756 (h) x 581 (w) pixels
- Pattern recognition: process-tolerant 256 grey level image processing with variable reference and search area and simple teach-in
- -Theta correction: +/- 7°
- -Accuracy: +/- 1/4 pixel
- -Recognition time: 50 - 100 mS per image